L Number	Hits	Search Text	DB	Time stamp
2	267521	package?	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 08:17
3	3744	ground$3 adj conductor?	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 08:22
4	12598	conduct$3 adj plate?	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 08:19
5	299	press adj block?	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 08:19
6	6	package? and (press adj block?)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 08:19
7	0	(ground$3 adj conductor?) and (conduct$3 adj plate?) and (press adj block?)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 08:22
8	0	(conduct$3 adj plate?) and (press adj block?)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 08:22
9	90	(ground$3 adj conductor?) and (conduct$3 adj plate?)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 08:22
10	10	((ground$3 adj conductor?) and (conduct$3 adj plate?)) and package?	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 08:26
11	294	package? and (ground$3 adj conductor?)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 08:26
12	62	(package? and (ground$3 adj conductor?)) and heat near5 (sink dissipation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 08:34
13	614	high adj frequency with (integrated adj circuit IC) with packag$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 08:34

14	65	(high adj frequency with (integrated adj circuit IC) with packag$3) and heat near5 (sink dissipation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 08:48
15	64	((high adj frequency with (integrated adj circuit IC) with packag$3) and heat near5 (sink dissipation)) not ((package? and (ground$3 adj conductor?)) and heat near5 (sink dissipation))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 08:35
16	24	(high adj frequency with (integrated adj circuit IC) with packag$3) and screws	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/26 08:48